


**PRODUCT / PROCESS CHANGE INFORMATION**

**1. PCI basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCI No.</b>	MDG/17/10568	
<b>1.3 Title of PCI</b>	New Tape Header finishing procedure for EEPROM in WLCSP (packed with EPE foam)	
<b>1.4 Product Category</b>	EEPROM in WLCSP	
<b>1.5 Issue date</b>	2017-11-21	

**2. PCI Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	MARSHALL DAVE
<b>2.1.2 Phone</b>	
<b>2.1.3 Email</b>	dave.marshall@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Benoit RODRIGUES
<b>2.1.2 Marketing Manager</b>	Hubert LEDUC
<b>2.1.3 Quality Manager</b>	Rita PAVANO

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Methods	Process flow chart: Revision change in Process/Recipe like addition, deletion of process step (process technology, sawing, die attach, plasma, marking, packing, labelling, transportation, etc..)	STATSChipPAC subcontractor

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	- In the current situation, the header is linked to the EPE foam, which is linked to the protective belt. Then placing (at finishing step) or removing (at customer unreeling step) the protective belt could induce tension to the tape.	With the new procedure, the header is pasted to itself (with ESD tape). The EPE foam is put in place and pasted to the protective belt. Then, the protective belt and the header being independent, removing the protective belt will have no action on the tape.
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	No impact	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	Reduction of potential tight winding of the tape.
<b>5.2 Customer Benefit</b>	QUALITY IMPROVEMENT

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	N/A
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2017-11-20
<b>7.2 Intended start of delivery</b>	2017-12-11
<b>7.3 Qualification sample available?</b>	Not Applicable

**8. Qualification / Validation**

<b>8.1 Description</b>	
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8.2 Qualification report and qualification results	In progress	Issue Date	
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<b>9. Attachments (additional documentations)</b>
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10568 Public product.pdf 10568 PCI End of Tape WLCSP ALL CUSTOMERS WITH EPE -1-.pdf
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<b>10. Affected parts</b>
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10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	M24128S-FCU6T/T	
	M24C16-DFCU6TP/K	

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